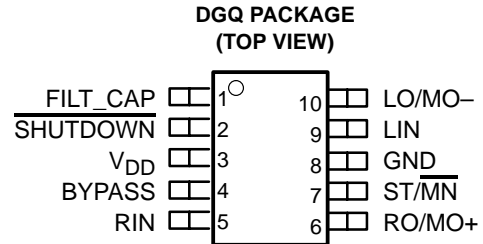


TPA0253

1-W MONO AUDIO POWER AMPLIFIER WITH HEADPHONE DRIVE

SLOS280D – JANUARY 2000 – REVISED NOVEMBER 2002

- Ideal for Notebook Computers, PDAs, and Other Small Portable Audio Devices
- 1 W Into 8-Ω From 5-V Supply
- 0.3 W Into 8-Ω From 3-V Supply
- Stereo Head Phone Drive
- Mono (BTL) Signal Created by Summing Left and Right Signals Internally
- Wide Power Supply Compatibility
2.5 V to 5.5 V
- Low Supply Current
 - 3.2 mA Typical at 5 V
 - 2.7 mA Typical at 3 V
- Shutdown Control . . . 1 μA Typical
- Shutdown Pin Is TTL Compatible
- –40°C to 85°C Operating Temperature Range
- Space-Saving, Thermally-Enhanced MSOP Packaging



description

The TPA0253 is a 1-W mono bridge-tied-load (BTL) amplifier designed to drive speakers with as low as 8-Ω impedance. The mono signal is created by summing left and right inputs internally. The amplifier can be reconfigured on the fly to drive two stereo single-ended (SE) signals into headphones. This makes the device ideal for use in small notebook computers, PDAs, digital personal audio players, anyplace a mono speaker and stereo headphones are required. From a 5-V supply, the TPA0253 can deliver 1-W of power into an 8-Ω speaker.

The gain of the input stage is set by the user-selected input resistor and a 50-kΩ internal feedback resistor ($A_V = -R_F/R_I$). The power stage is internally configured with a gain of –1.25 V/V in SE mode, and –2.5 V/V in BTL mode. Thus, the overall gain of the amplifier is 62.5 kΩ/R_I in SE mode and 125 kΩ/R_I in BTL mode. The input terminals are high-impedance CMOS inputs, and can be used as summing nodes.

The TPA0253 is available in the 10-pin thermally-enhanced MSOP package (DGQ) and operates over an ambient temperature range of –40°C to 85°C.

AVAILABLE OPTIONS

| T _A | PACKAGED DEVICES | MSOP SYMBOLIZATION |
|----------------|------------------|--------------------|
| | MSOP† (DGQ) | |
| –40°C to 85°C | TPA0253DGQ | AEL |

† The DGQ package are available taped and reeled. To order a taped and reeled part, add the suffix R to the part number (e.g., TPA0253DGQR).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

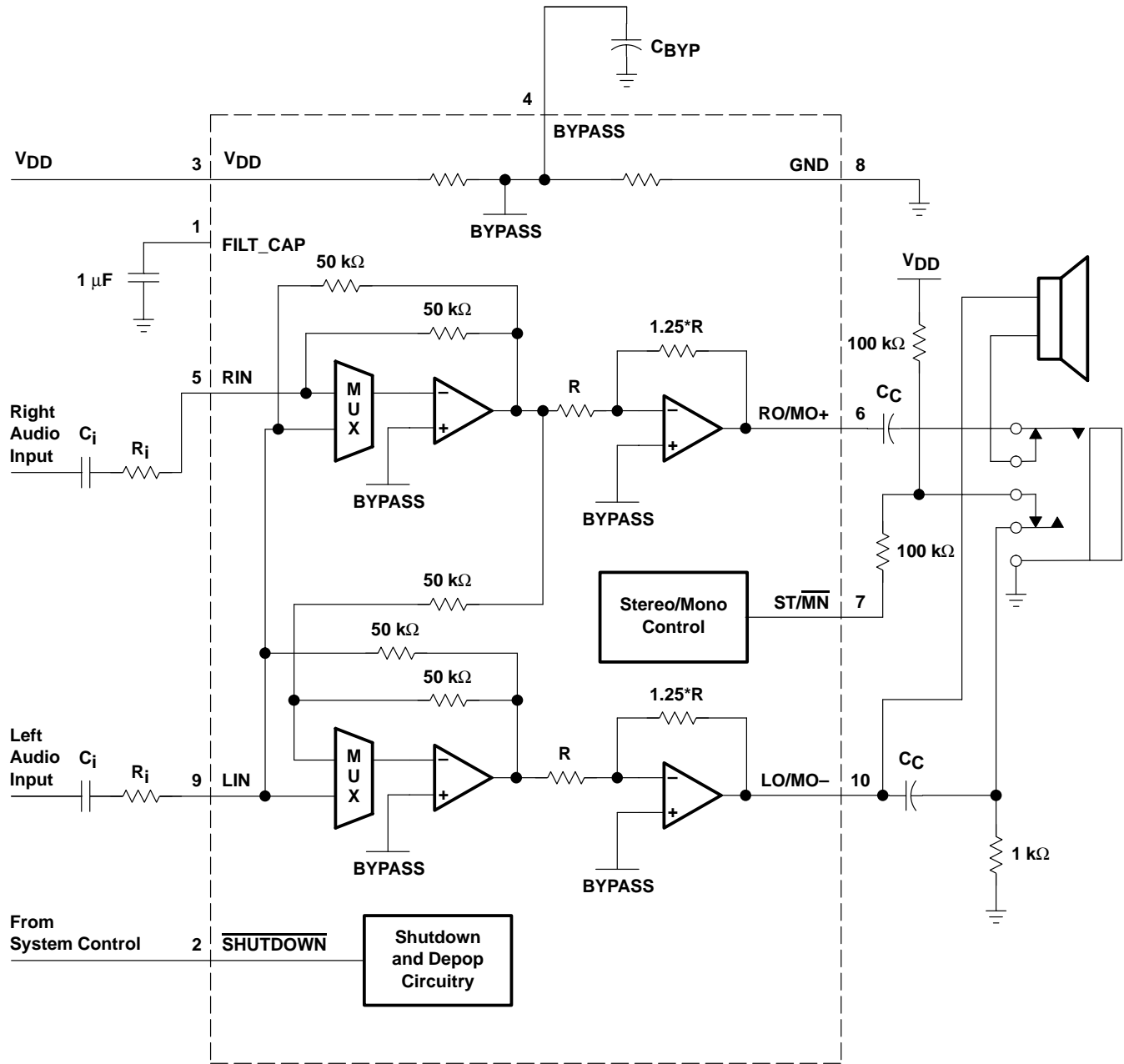
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TPA0253 1-W MONO AUDIO POWER AMPLIFIER WITH HEADPHONE DRIVE

SLOS280D – JANUARY 2000 – REVISED NOVEMBER 2002

schematic



Terminal Functions

| TERMINAL NAME | NO. | I/O | DESCRIPTION |
|-----------------|-----|-----|--|
| BYPASS | 4 | I | Midrail bias voltage |
| FILT_CAP | 1 | | Terminal used to filter power supply |
| GND | 8 | | Ground terminal |
| LIN | 9 | I | Left-channel input terminal |
| LO/MO- | 10 | O | Left-output in SE mode and mono negative output in BTL mode. |
| RIN | 5 | I | Right-channel input terminal |
| RO/MO+ | 6 | O | Right-output in SE mode and mono positive output in BTL mode |
| SHUTDOWN | 2 | I | TTL-compatible shutdown terminal |
| ST/MN | 7 | I | Selects between stereo and mono mode. When held high, the amplifier is in SE stereo mode; while held low, the amplifier is in BTL mono mode. |
| V _{DD} | 3 | I | Positive power supply |

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

| | |
|--|---|
| Supply voltage, V _{DD} | 6 V |
| Input voltage range, V _I | -0.3 V to V _{DD} +0.3 V |
| Continuous total power dissipation | internally limited (see Dissipation Rating Table) |
| Operating free-air temperature range, T _A (see Table 3) | -40°C to 85°C |
| Operating junction temperature range, T _J | -40°C to 150°C |
| Storage temperature range, T _{stg} | -65°C to 150°C |
| Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds | 260°C |

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

DISSIPATION RATING TABLE

| PACKAGE | T _A ≤ 25°C | DERATING FACTOR | T _A = 70°C | T _A = 85°C |
|---------|-----------------------|-----------------|-----------------------|-----------------------|
| DGQ | 2.14 W [‡] | 17.1 mW/°C | 1.37 W | 1.11 W |

‡ Please see the Texas Instruments document, *PowerPAD Thermally Enhanced Package Application Report* (SLMA002), for more information on the PowerPAD™ package. The thermal data was measured on a PCB layout based on the information in the section entitled *Texas Instruments Recommended Board for PowerPAD* on page 33 of that document.

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1-W MONO AUDIO POWER AMPLIFIER
WITH HEADPHONE DRIVE

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recommended operating conditions

| | | | MIN | MAX | UNIT |
|---------------------------------------|----------|-----------------------|-----|------|------|
| Supply voltage, V_{DD} | | | 2.5 | 5.5 | V |
| High-level input voltage, V_{IH} | ST/MN | $V_{DD} = 3\text{ V}$ | 2.7 | | V |
| | | $V_{DD} = 5\text{ V}$ | 4.5 | | |
| | SHUTDOWN | | 2 | | |
| Low-level input voltage, V_{IL} | ST/MN | $V_{DD} = 3\text{ V}$ | | 1.65 | V |
| | | $V_{DD} = 5\text{ V}$ | | 2.75 | |
| | SHUTDOWN | | | 0.8 | |
| Operating free-air temperature, T_A | | | -40 | 85 | °C |

electrical characteristics at specified free-air temperature, $V_{DD} = 3\text{ V}$, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|--------------|---|---|-----|-----|-----|---------------|
| $ V_{OO} $ | Output offset voltage (measured differentially) | $R_L = 4\ \Omega$, ST/MN = 0 V, SHUTDOWN = 2 V | | | 30 | mV |
| PSRR | Power supply rejection ratio | $V_{DD} = 2.9\text{ V to } 3.1\text{ V}$, BTL mode | | 65 | | dB |
| $ I_{IH} $ | High-level input current | SHUTDOWN, $V_{DD} = 3.3\text{ V}$, $V_I = V_{DD}$ | | | 1 | μA |
| | | ST/MN, $V_{DD} = 3.3\text{ V}$, $V_I = V_{DD}$ | | | 1 | |
| $ I_{IL} $ | Low-level input current | SHUTDOWN, $V_{DD} = 3.3\text{ V}$, $V_I = 0\text{ V}$ | | | 1 | μA |
| | | ST/MN, $V_{DD} = 3.3\text{ V}$, $V_I = 0\text{ V}$ | | | 1 | |
| Z_I | Input impedance | | | 50 | | k Ω |
| I_{DD} | Supply current | $V_{DD} = 2.5\text{ V}$, SHUTDOWN = 2 V | | 2.7 | 4 | mA |
| $I_{DD(SD)}$ | Supply current, shutdown mode | SHUTDOWN = 0 V | | 1 | 10 | μA |
| R_F | Feedback resistor | $V_{DD} = 2.5\text{ V}$, $R_L = 4\ \Omega$, ST/MN = 1.375 V, SHUTDOWN = 2 V | 47 | 50 | 57 | k Ω |

operating characteristics, $V_{DD} = 3\text{ V}$, $T_A = 25^\circ\text{C}$, $R_L = 8\ \Omega$, $f = 1\text{ kHz}$ (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|-----------|--------------------------------------|--|----------|------|-----|---------------------|
| P_O | Output power, see Note 1 | THD = 0.1%, BTL mode, Gain = 14 dB | | 300 | | mW |
| | | THD = 0.1%, SE mode, $R_L = 32\ \Omega$, Gain = 1.9 dB | | 30 | | |
| THD + N | Total harmonic distortion plus noise | $P_O = 250\text{ mW}$, $f = 20\text{ Hz to } 20\text{ kHz}$ | | 0.2% | | |
| BOM | Maximum output power bandwidth | Gain = 1.9 dB, THD = 2% | | 20 | | kHz |
| | Supply ripple rejection ratio | $f = 1\text{ kHz}$, $C_{(BYP)} = 0.47\ \mu\text{F}$ | BTL mode | 46 | | dB |
| | | | SE mode | 68 | | |
| V_n | Noise output voltage | $C_{(BYP)} = 0.47\ \mu\text{F}$, $f = 20\text{ Hz to } 20\text{ kHz}$ | BTL mode | 83 | | μV_{RMS} |
| | | | SE mode | 33 | | |

NOTE 1: Output power is measured at the output terminals of the device at $f = 1\text{ kHz}$.



TPA0253
1-W MONO AUDIO POWER AMPLIFIER
WITH HEADPHONE DRIVE

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electrical characteristics at specified free-air temperature, $V_{DD} = 5\text{ V}$, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|--------------|---|--|-----|-----|-----|---------------|
| $ V_{OO} $ | Output offset voltage (measured differentially) | $R_L = 4\ \Omega$, $ST/MN = 0\text{ V}$, $SHUTDOWN = 2\text{ V}$ | | | 30 | mV |
| PSRR | Power supply rejection ratio | $V_{DD} = 4.9\text{ V}$ to 5.1 V , BTL mode | | 62 | | dB |
| $ I_{IH} $ | High-level input current | $SHUTDOWN$, $V_{DD} = 5.5\text{ V}$, $V_I = V_{DD}$ | | | 1 | μA |
| | | ST/MN , $V_{DD} = 5.5\text{ V}$, $V_I = V_{DD}$ | | | 1 | |
| $ I_{IL} $ | Low-level input current | $SHUTDOWN$, $V_{DD} = 5.5\text{ V}$, $V_I = 0\text{ V}$ | | | 1 | μA |
| | | ST/MN , $V_{DD} = 5.5\text{ V}$, $V_I = 0\text{ V}$ | | | 1 | |
| Z_I | Input impedance | | | 50 | | k Ω |
| I_{DD} | Supply current | $SHUTDOWN = 2\text{ V}$ | | 3.2 | 4.8 | mA |
| $I_{DD(SD)}$ | Supply current, shutdown mode | $SHUTDOWN = 0\text{ V}$ | | 1 | 10 | μA |

operating characteristics, $V_{DD} = 5\text{ V}$, $T_A = 25^\circ\text{C}$, $R_L = 8\ \Omega$, $f = 1\text{ kHz}$ (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | | MIN | TYP | MAX | UNIT |
|-----------|--------------------------------------|-----------------------------------|---------------------------------------|----------|-------|-----|------------------|
| P_O | Output power (see Note 1) | THD = 0.1%, | BTL mode | | 1 | | W |
| | | THD = 0.1%, | SE mode, $R_L = 32\ \Omega$ | | 85 | | mW |
| THD + N | Total harmonic distortion plus noise | $P_O = 1\text{ W}$, | $f = 20\text{ Hz}$ to 20 kHz | | 0.33% | | |
| BOM | Maximum output power bandwidth | Gain = 8 dB, | THD = 2% | | 20 | | kHz |
| | Supply ripple rejection ratio | $f = 1\text{ kHz}$, | $C_{(BYP)} = 0.47\ \mu\text{F}$ | BTL mode | 46 | | dB |
| | | | | SE mode | 60 | | |
| V_n | Noise output voltage | $C_{(BYP)} = 0.47\ \mu\text{F}$, | $f = 20\text{ Hz}$ to 20 kHz | BTL mode | 85 | | μVRMS |
| | | | | SE mode | 34 | | |

NOTE 1: Output power is measured at the output terminals of the device at $f = 1\text{ kHz}$.

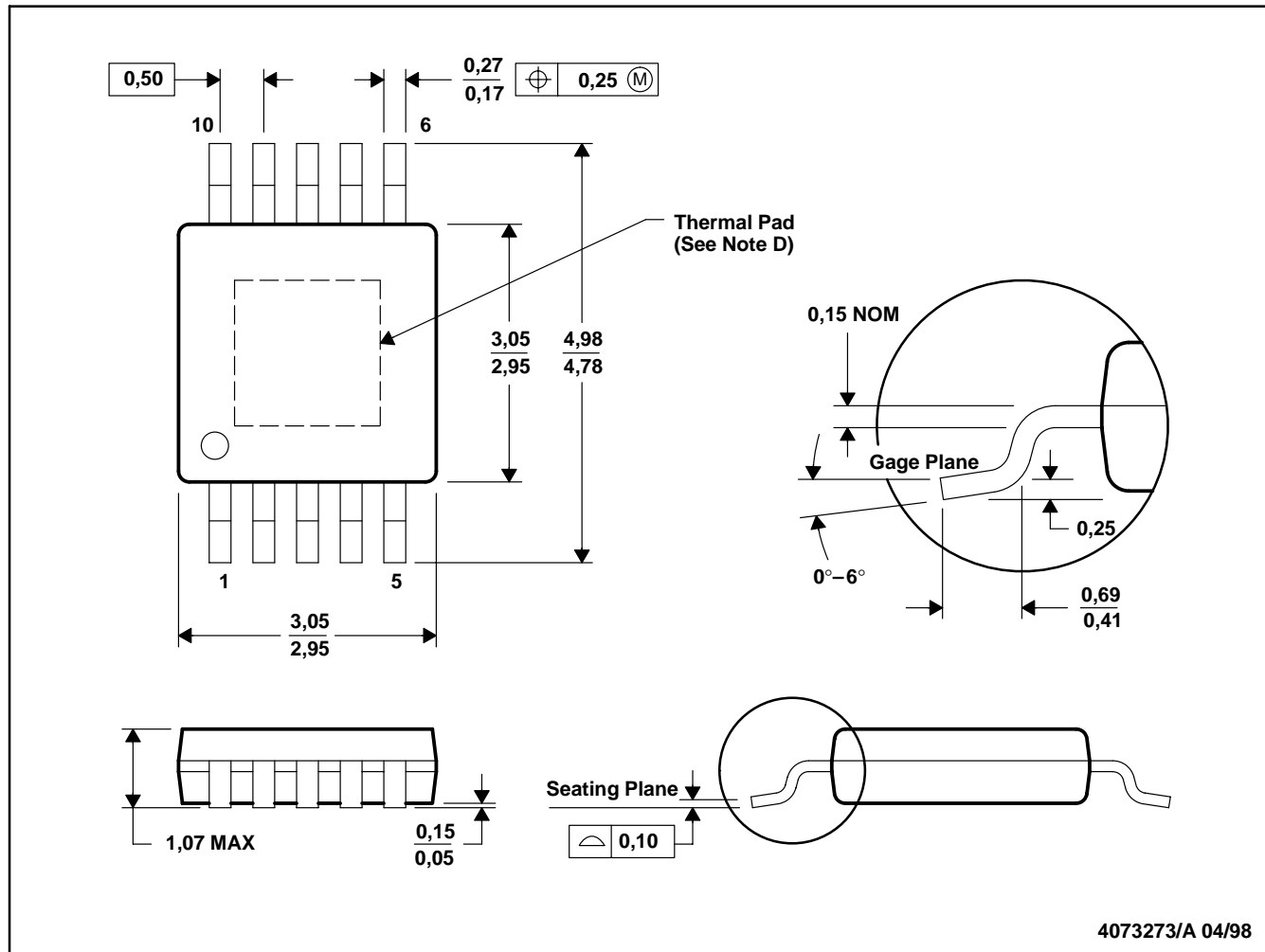
TPA0253
1-W MONO AUDIO POWER AMPLIFIER
WITH HEADPHONE DRIVE

SLOS280D – JANUARY 2000 – REVISED NOVEMBER 2002

MECHANICAL DATA

DGQ (S-PDSO-G10)

PowerPAD™ PLASTIC SMALL-OUTLINE PACKAGE



4073273/A 04/98

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion.
 D. The package thermal performance may be enhanced by bonding the thermal pad to an external thermal plane.
 This pad is electrically and thermally connected to the backside of the die and possibly selected leads. The dimension of the thermal pad is 1,40 mm (height as illustrated) × 1,80 (width as illustrated) mm (maximum). The pad is centered on the bottom of the package.

PowerPAD is a trademark of Texas Instruments.



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PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|----------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| TPA0253DGQ | ACTIVE | MSOP-Power PAD | DGQ | 10 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TPA0253DGQG4 | ACTIVE | MSOP-Power PAD | DGQ | 10 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TPA0253DGQR | ACTIVE | MSOP-Power PAD | DGQ | 10 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TPA0253DGQRG4 | ACTIVE | MSOP-Power PAD | DGQ | 10 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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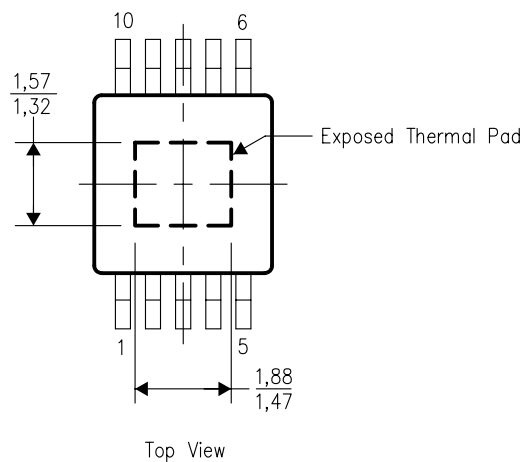
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THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. When the thermal pad is soldered directly to the printed circuit board (PCB), the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to a ground or power plane (whichever is applicable), or alternatively, a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at www.ti.com.

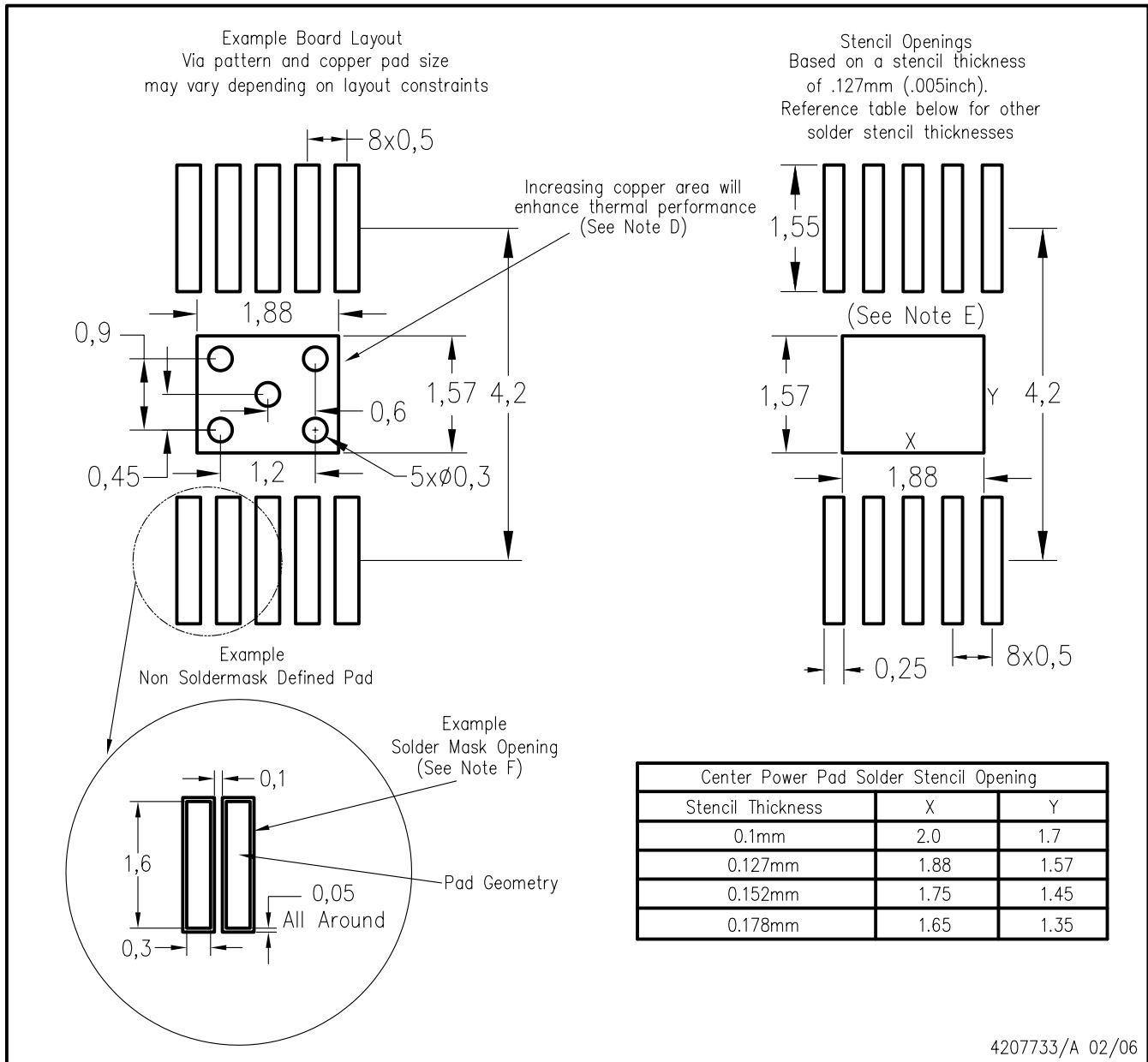
The exposed thermal pad dimensions for this package are shown in the following illustration.



NOTE: All linear dimensions are in millimeters

Exposed Thermal Pad Dimensions

DGQ (R-PDSO-G10) PowerPAD™



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002, SLMA004, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.
 - F. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|----------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| TPA0253DGQ | ACTIVE | MSOP-Power PAD | DGQ | 10 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TPA0253DGQG4 | ACTIVE | MSOP-Power PAD | DGQ | 10 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TPA0253DGQR | ACTIVE | MSOP-Power PAD | DGQ | 10 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TPA0253DGQRG4 | ACTIVE | MSOP-Power PAD | DGQ | 10 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |

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OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

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Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-------------|----------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| TPA0253DGQR | MSOP-Power PAD | DGQ | 10 | 2500 | 330.0 | 13.0 | 5.3 | 3.4 | 1.4 | 8.0 | 12.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS

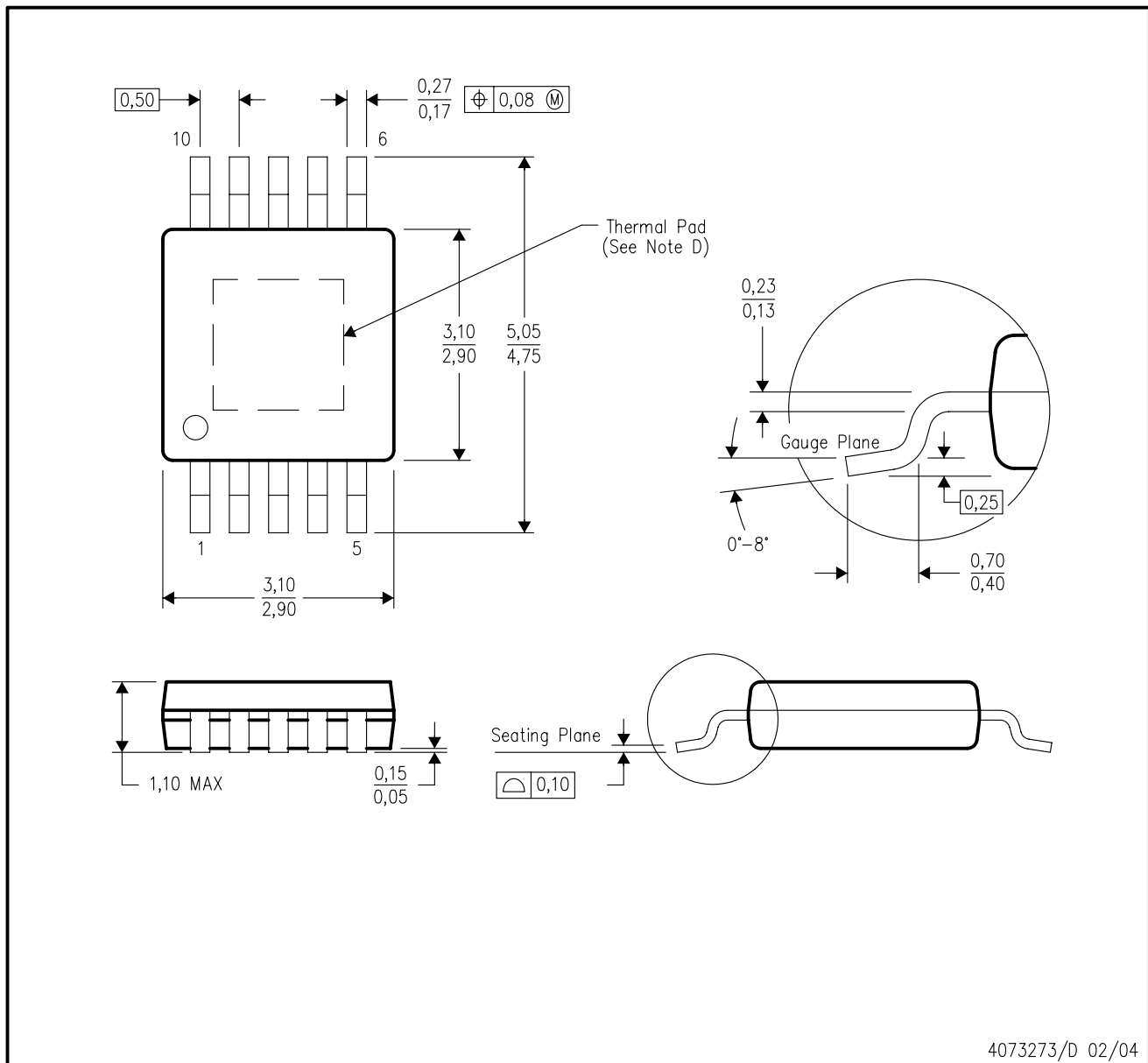


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-------------|---------------|-----------------|------|------|-------------|------------|-------------|
| TPA0253DGQR | MSOP-PowerPAD | DGQ | 10 | 2500 | 358.0 | 335.0 | 35.0 |

DGQ (S-PDSO-G10)

PowerPAD™ PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion.
 - This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <<http://www.ti.com>>.
 - Falls within JEDEC MO-187 variation BA-T.

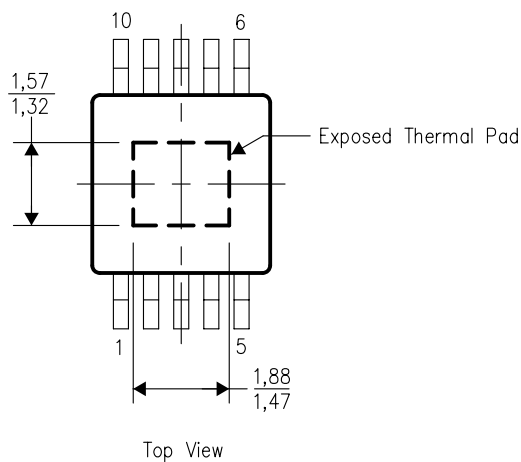
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THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at www.ti.com.

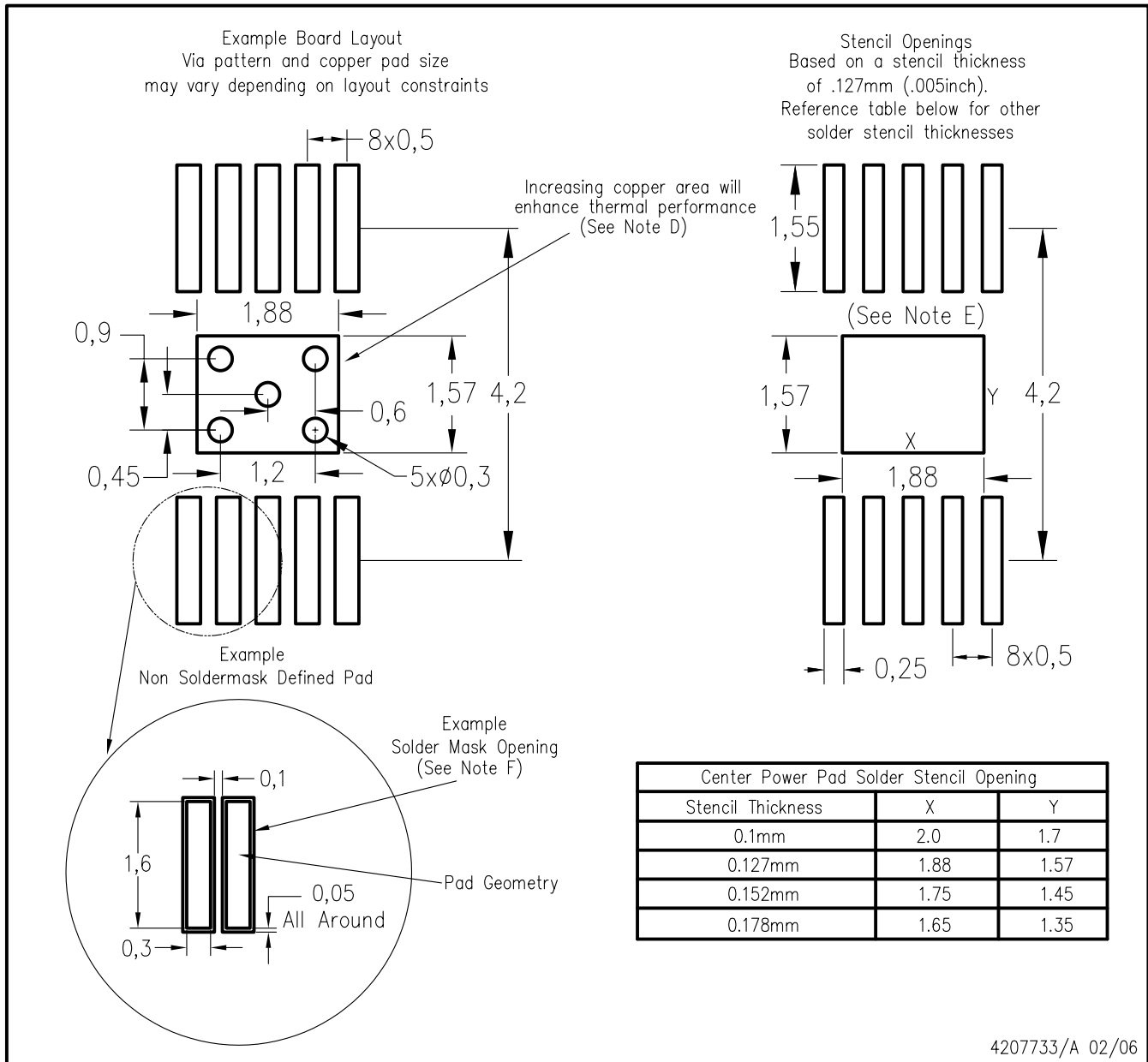
The exposed thermal pad dimensions for this package are shown in the following illustration.



NOTE: All linear dimensions are in millimeters

Exposed Thermal Pad Dimensions

DGQ (R-PDSO-G10) PowerPAD™



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002, SLMA004, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.
 - F. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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